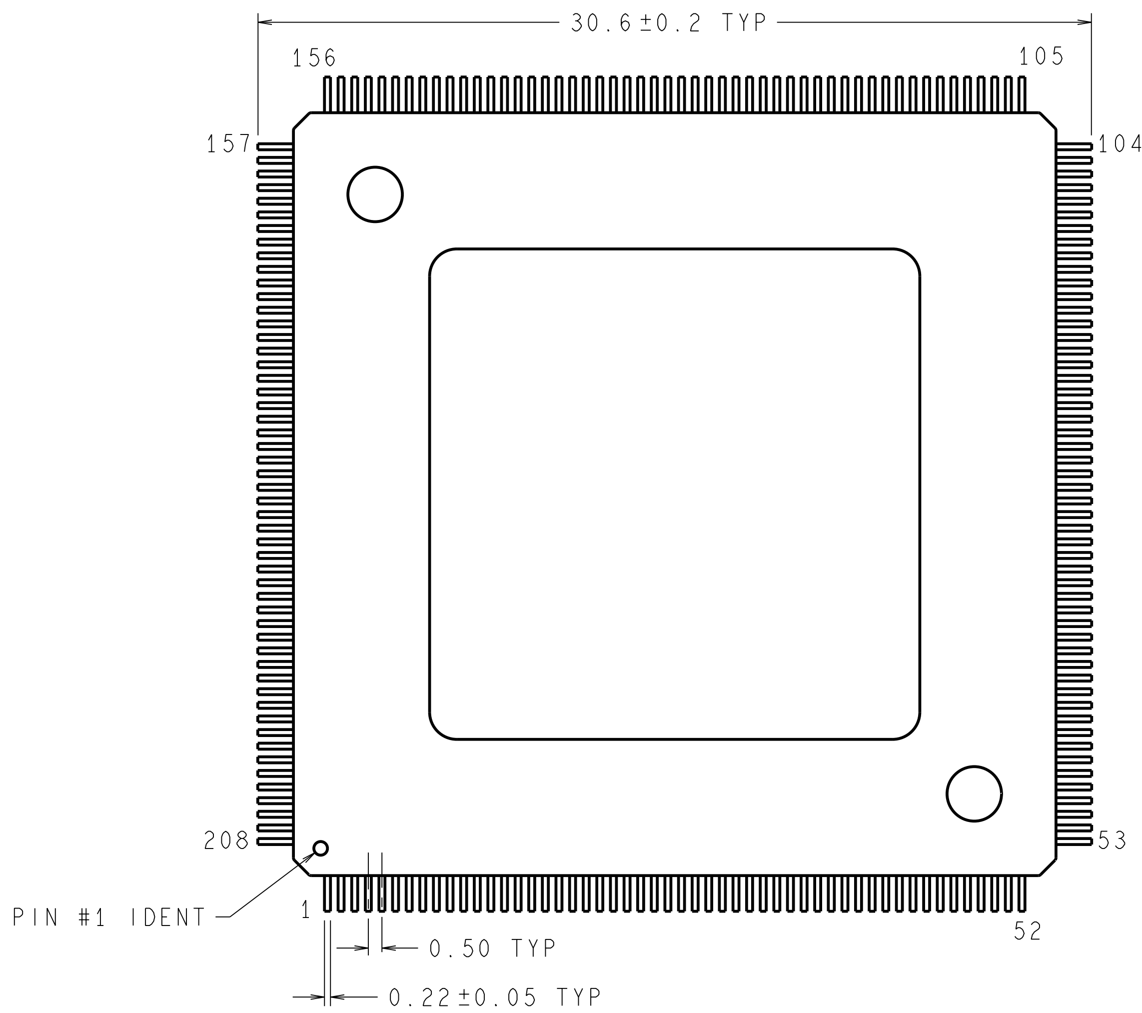
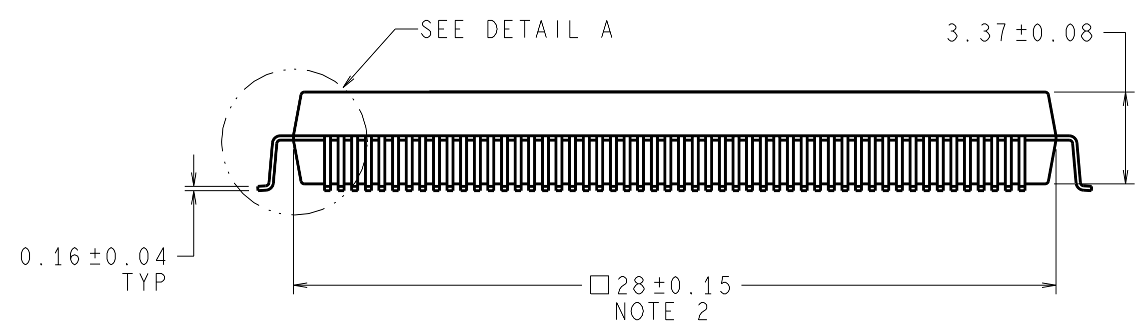
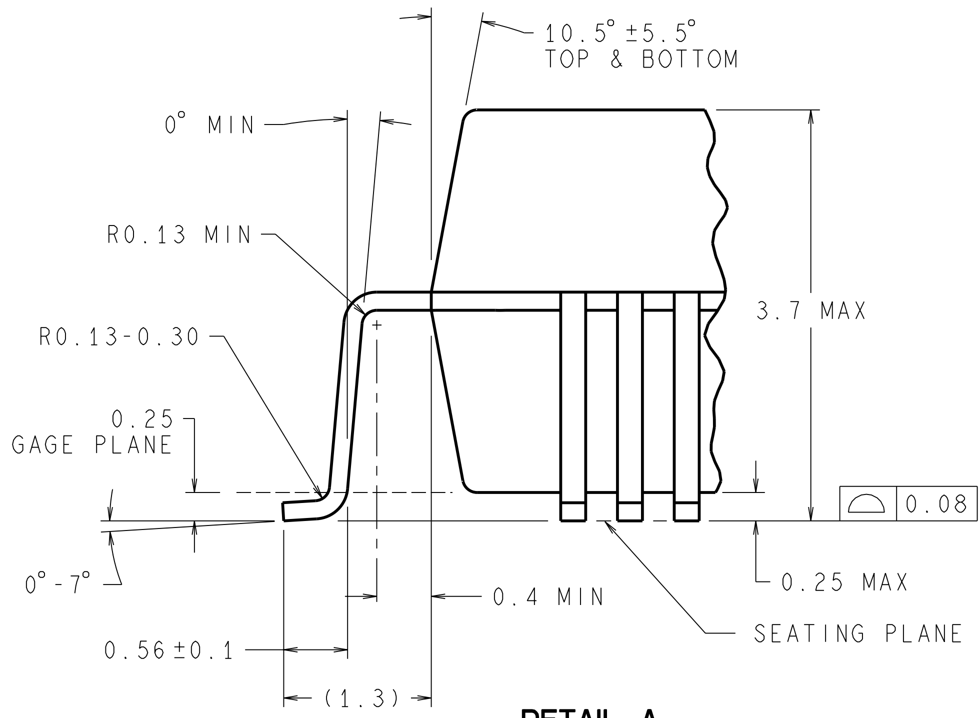
REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	10680	11/17/1994	KES/HJK
B	REV NOTES,H/S,MOLD DIM & LD FORM DIM'S	12303	09/22/1999	TL/RW







DETAIL A
TYPICAL,SCALE:25X

DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

1. STANDARD LEAD FINISH:
   7.62 MICROMETERS MINIMUM SOLDER PLATING (85/15)
   THICKNESS ON COPPER.
2. DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.
   MAXIMUM ALLOWABLE MOLD PROTRUSION 0.25mm PER SIDE.
3. REFERENCE JEDEC REGISTRATION MS-029, VARIATION FA-2,
   DATED AUGUST 1997.

APPROVALS	DATE
DRAWN KURT SINCERBOX	11/17/1994
DFTG. CHK. MARTA SUCHY	09/22/1999
ENGR. CHK. RANDY WALBERG	09/22/1999

National Semiconductor
2900 Semiconductor dr, Santa Clara, CA 95052-8090

PQFP,JEDEC METRIC,
28 X 28 X 3.4mm,
208 LEAD,TEPP

PROJECTION INCH [MM]

SCALE	SIZE	DRAWING NUMBER	REV
N/A	C	(SC)MKT-VQM208A	B

DO NOT SCALE DRAWING — SHEET 1 of 1